



## Description

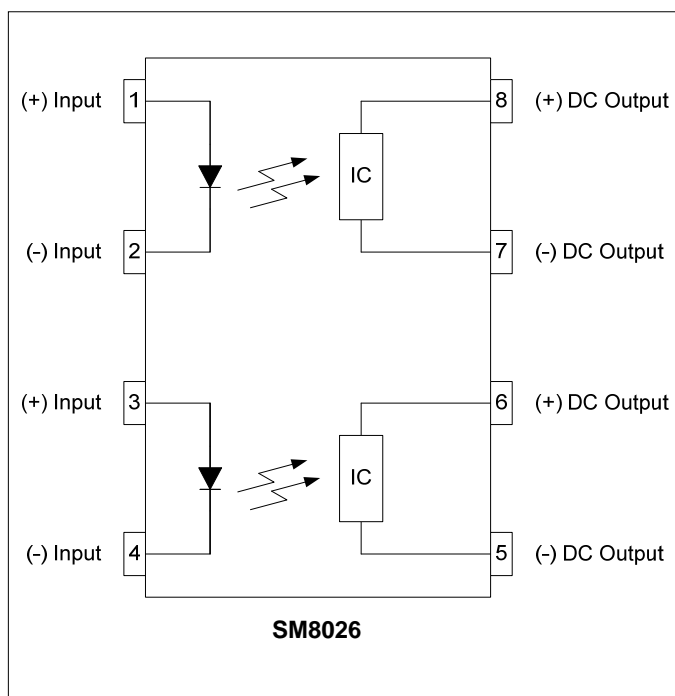
The SM8026 is composed of two distinct MOSFET drivers in a single package. Each driver circuit consists of an input drive LED optically coupled to a photodiode array output designed to drive highly capacitive loads, including the gate of a power MOSFET. The active discharge circuit of the PDAs assures quick discharge of MOSFETs, providing fast turn-off times. This device can be used as two separate drivers, or can be wired as a single enhanced driver with either greater photo current or photo voltage output.

The SM8026 comes standard in a compact 8 pin DIP package making it ideal for high-density board applications.

## Applications

- Isolated means to drive discrete power MOSFETs
- Lighting Controls
- Process Control Modules
- Solid State Relays
- Solenoid Controls

## Schematic Diagram



## Features

- Compact 8 pin DIP/SMD package
- Built in active discharge circuit for fast turn-off
- Fast Turn-On
- Optional Parallel or Serial Output Connections
- 11V Gate Drive Voltage
- High Input-to-Output Isolation (up to 5kV<sub>RMS</sub>)
- Long Life / High Reliability
- RoHS / Pb-Free / REACH Compliant

## Agency Approvals

UL/C-UL: File # E201932  
VDE: File # 40035191 (EN 60747-5-2)

## Absolute Maximum Ratings

The values indicated are absolute stress ratings. Functional operation of the device is not implied at these or any conditions in excess of those defined in electrical characteristics section of this document. Exposure to absolute Maximum Ratings may cause permanent damage to the device and may adversely affect reliability.

Storage Temperature .....-55 to +125°C  
Operating Temperature .....-40 to +85°C  
Continuous Input Current .....50mA  
Transient Input Current .....400mA  
Reverse Input Control Voltage .....5V  
Input Power Dissipation .....40mW  
Output Power Dissipation .....400mW  
Solder Temperature – Wave (10sec).....260°C  
Solder Temperature – IR Reflow (10sec).....260°C

## Ordering Information

Part Number	Description
SM8026	8 pin DIP, (50/Tube)
SM8026-H	5kV <sub>RMS</sub> Viso, 8 pin DIP, (50/Tube)
SM8026-S	8 pin SMD, (50/Tube)
SM8026-HS	5kV <sub>RMS</sub> , 8 pin SMD, (50/Tube)
SM8026-STR	8 pin SMD, Tape and Reel (1000/Reel)
SM8026-HSTR	5kV <sub>RMS</sub> , 8 pin SMD, Tape and Reel (1000/Reel)

**NOTE: Suffixes listed above are not included in marking on device for part number identification**

**Electrical Characteristics,  $T_A = 25^\circ\text{C}$  (unless otherwise specified)**

Parameter	Symbol	Min.	Typ.	Max.	Units	Test Conditions
<b>Input Specifications</b>						
LED Forward Voltage	$V_F$	-	2.4	2.6	V	$I_F = 10\text{mA}$
LED Reverse Voltage	$BV_R$	5	-	-	V	$I_R = 10\mu\text{A}$
Reverse Leakage Current	$I_{InRleak}$	-	-	10	$\mu\text{A}$	$V_R = 5\text{V}$
Turn-On Current	$I_F$	-	5	10	mA	$V_{OUT} = 5\text{V}$
Turn-Off Current	$I_{F(OFF)}$	-	0.5	-	mA	$V_{OUT} = 2\text{V}$
<b>Output Specifications</b>						
Open Circuit Voltage	$V_{OC}$	11	12	-	V	$I_F = 10\text{mA}$
Short Circuit Voltage	$I_{SC}$	3	4	-	$\mu\text{A}$	$I_F = 10\text{mA}$
<b>Isolation Specifications</b>						
Isolation Voltage (-H Option)	$V_{ISO}$	3750	-	-	$V_{RMS}$	RH $\leq$ 50%, t=1min
		5000	-	-		
Input-Output Resistance	$R_{I-O}$	-	$10^{12}$	-	$\Omega$	$V_{I-O} = 500V_{DC}$

**SM8026 Solder Temperature Profile Recommendations**
**(1) Infrared Reflow:**

Refer to the following figure as an example of an optimal temperature profile for single occurrence infrared reflow. Soldering process should not exceed temperature or time limits expressed herein. Surface temperature of device package should not exceed 250°C:

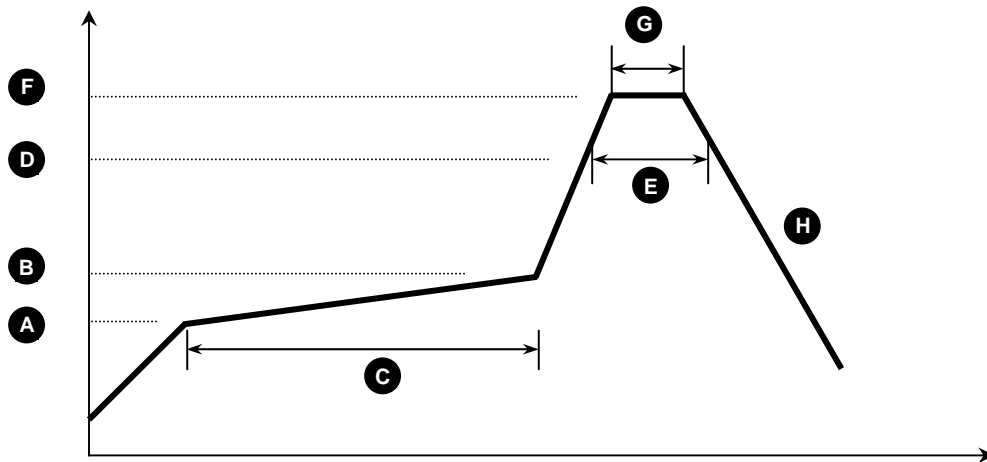


Figure 1

Process Step	Description	Parameter
<b>A</b>	Preheat Start Temperature (°C)	150°C
<b>B</b>	Preheat Finish Temperature (°C)	180°C
<b>C</b>	Preheat Time (s)	90 - 120s
<b>D</b>	Melting Temperature (°C)	230°C
<b>E</b>	Time above Melting Temperature (s)	30s
<b>F</b>	Peak Temperature, at Terminal (°C)	260°C
<b>G</b>	Dwell Time at Peak Temperature (s)	10s
<b>H</b>	Cool-down (°C/s)	<6°C/s

**(2) Wave Solder:**

Maximum Temperature: 260°C (at terminal)  
 Maximum Time: 10s  
 Pre-heating: 100 - 150°C (30 - 90s)  
 Single Occurrence

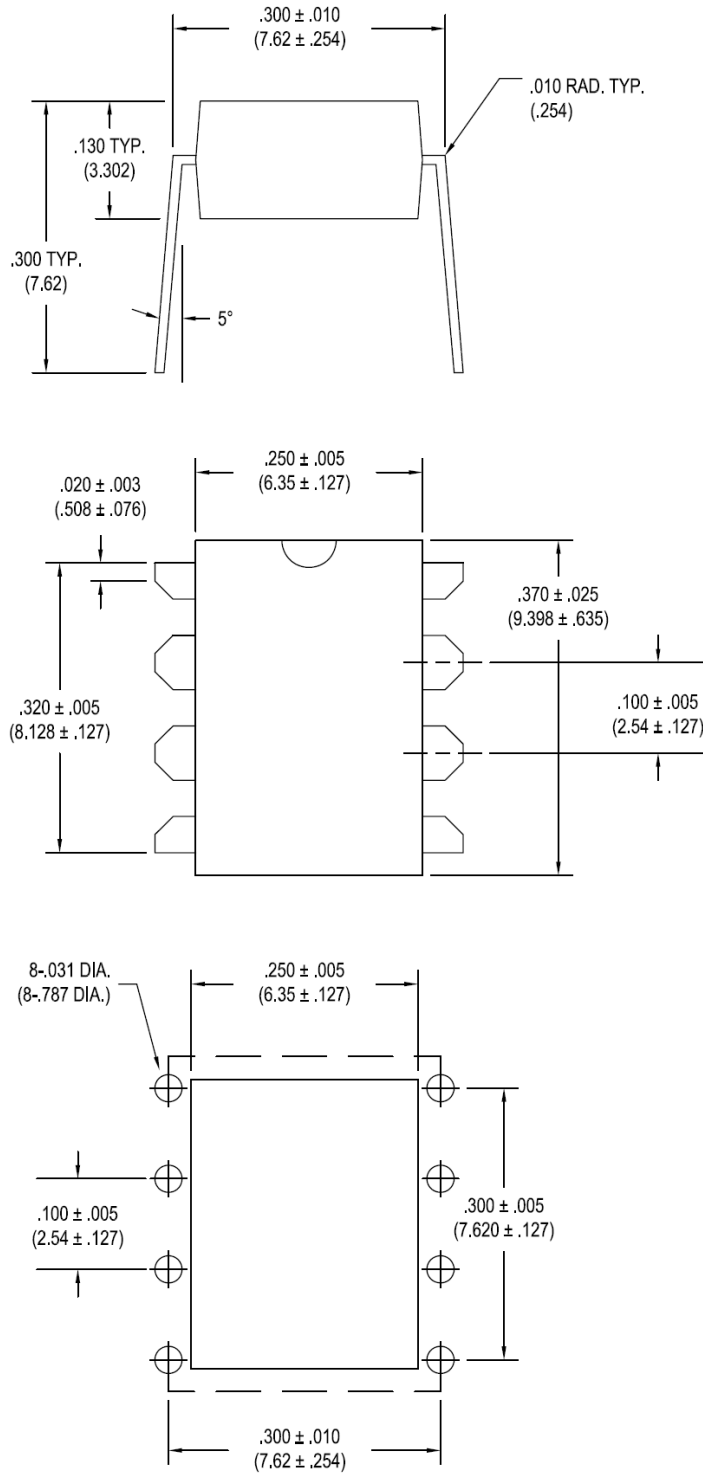
**(3) Hand Solder:**

Maximum Temperature: 350°C (at tip of soldering iron)  
 Maximum Time: 3s  
 Single Occurrence

**SM8026 Package Dimensions**

8 PIN DIP Package

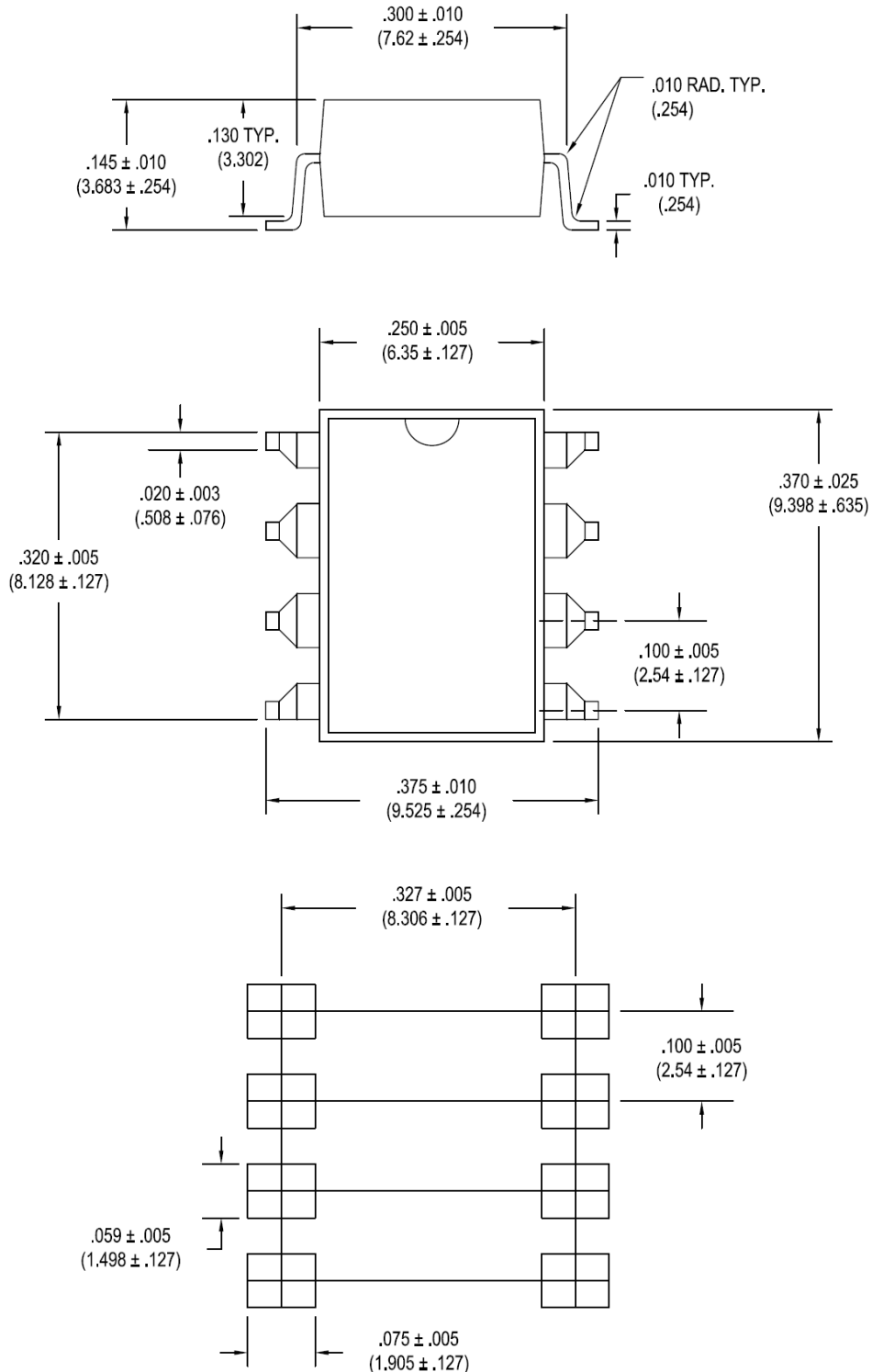
**Note:** All dimensions in inches ["] with millimeters in parenthesis ( )



**SM8026 Package Dimensions**

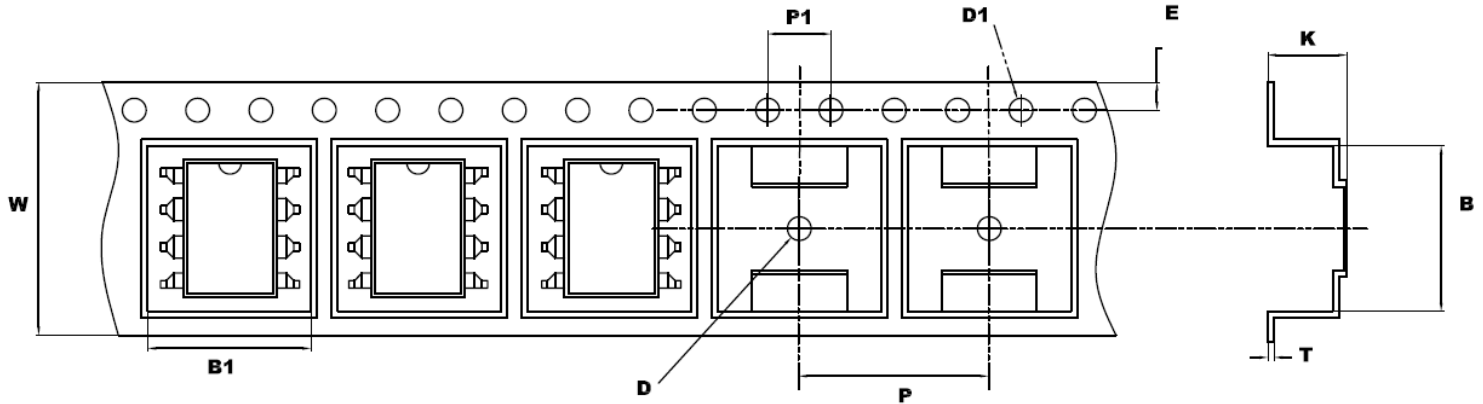
8 PIN SMD Surface Mount Package (-S)

**Note:** All dimensions in inches ["] with millimeters in parenthesis ( )

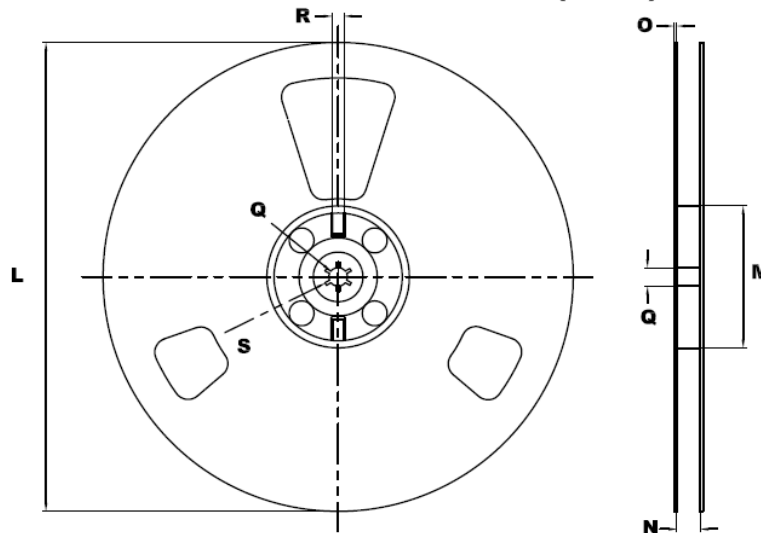


**SM8026 Package Dimensions**

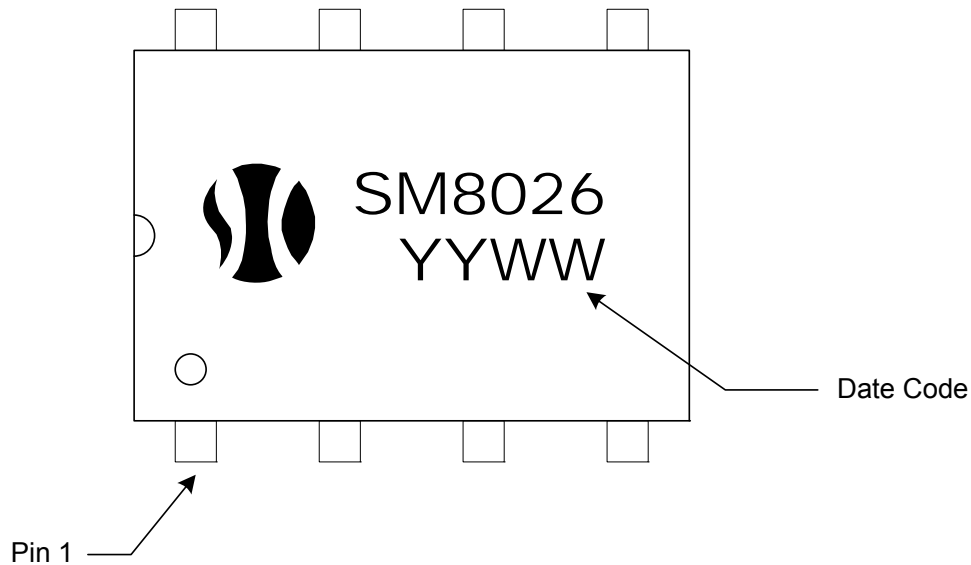
8 PIN SMD Tape &amp; Reel (-STR)

*Note: All dimensions in millimeters*
**Outline and Dimension (Tape)**

 Direction of Feed  $\longrightarrow$ 

W	B	B1	P	P1	K	E	T	D	D1
16.00 ±0.1	10.50 ±0.1	10.30 ±0.1	12.00 ±0.1	4.00 ±0.1	5.00 ±0.1	1.75 ±0.1	0.40 ±0.1	1.50 ±0.1	1.50 ±0.1

**Outline and Dimensions (Reel)**

**Packaging: 1,000 pcs / reel**

L	M	N	O	Q	R	S
330.00	100.00	16.40 ±0.2	2.00 ±0.1	13.00 ±0.2	2.00	10.00

**SM8026 Package Marking**

**SM8026 Package Weights**

Device	Single Unit	Full Tube (50pcs)	Full Pouch (10 tubes)	Full Reel (1000pcs)
SM8026(-H)	0.54	43	450	-
SM8026(-H)S	0.53	42	440	-
SM8026(-H)STR	0.53	-	-	952

**Note:** All weights above are in GRAMS, and include packaging materials where applicable

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